

ORIGINAL

CRISPIN & BRENNER, P.L.L.C.

1156 15TH STREET, N.W.

SUITE 1105

WASHINGTON, D.C. 20005

(202) 828-0152

(202) 828-0158 (FAX)

EX PARTE OR LATE FILED

RECEIVED

JUL 18 2001

FEDERAL COMMUNICATIONS COMMISSION
OFFICE OF THE SECRETARY

WRITER'S DIRECT NO.

(202) 828-0155

July 18, 2001

Ms. Magalie R. Salas
Federal Communications Commission
445 12th Street, S.W.
Washington, D.C. 20554

Re: Oral Ex Parte Presentation

CC Docket No. 94-102; ET Docket No. 00-258

Dear Ms. Salas:

On behalf of my client QUALCOMM Incorporated ("QUALCOMM"), this is to report that on July 17, 2001, Dr. Irwin Jacobs, CEO of QUALCOMM, Kevin Kelley, Senior Vice President, External Affairs of QUALCOMM, Jonas Neihardt, Vice President, Federal Affairs of QUALCOMM, and I met with Chairman Michael Powell and Peter Tenhula, Senior Legal Advisor to Chairman Powell to discuss matters related to the two proceedings referenced above.

With respect to CC Docket No. 94-102, Dr. Jacobs explained that QUALCOMM was on schedule in the production of chips and software for wireless assisted GPS phones, consistent with the deadlines in the FCC's rules for the deployment of E911 handset solutions by wireless carriers. Dr. Jacobs also explained that the chips being shipped at present in commercial quantities are for 2G wireless systems, but that QUALCOMM is now also shipping samples of chips with the 1x mode of third generation (3G) technology and wireless assisted GPS capability.

Dr. Jacobs also described the very successful initial results of the first widespread commercial launch of QUALCOMM's wireless assisted GPS position location technology, gpsOne, in Japan by SECOM Co. Ltd. ("SECOM"). SECOM is marketing wireless location devices with gpsOne over KDDI's wireless system, and the initial results have been very positive. (These initial results are more fully described in my ex parte letter to the Commission dated April 25, 2001.) Dr. Jacobs said that the results of the SECOM deployment, along with QUALCOMM's progress to date in shipping chips and software to handset manufacturers, show that handset-assisted wireless location technology is available, affordable, and reliable.

With respect to ET Docket No. 00-258, Dr. Jacobs discussed the status of the commercial

deployments of third generation (3G) cdma2000 1x in Korea, Japan, and the United States, which are on schedule with prior announcements from QUALCOMM and various carriers. Dr. Jacobs also discussed the inherent advantages to operators of deploying cdma2000 1x and cdma2000 1xEV in terms of reduced costs, higher data rates, and greater capacity than other 3G technologies. Dr. Jacobs said that U.S. wireless carriers do not need additional spectrum to deploy these 3G technologies.

Dr. Jacobs also reported to Chairman Powell on the status of efforts to deploy CDMA technology at 450 MHz in various European countries, including Romania. In Romania, a 3G system using cdma 1x technology will be deployed in the 450 MHz band, in which the carrier has a license for 10 MHz of spectrum.

Finally, Dr. Jacobs provided Chairman Powell with background information related to BREW, QUALCOMM's platform to enable third party software developers to write applications for wireless phones. At present, third party software developers have had difficulties writing applications for wireless phones because of the absence of a common platform covering all the various handsets manufactured by different manufacturers. BREW will provide software developers with such a common platform. Dr. Jacobs explained that BREW applications will reside on the servers of wireless carriers, and customers will be able to download the applications directly into their phones. Dr. Jacobs described the types of applications which BREW will enable, including location-based applications, games, and other internet-related services.

Please contact me if you need any further information.

Sincerely yours,



Dean R. Brenner

Attorney for QUALCOMM Incorporated

cc: Chairman Michael Powell
Peter Tenhula

F:\Clients\QUALCOMM\7-17-01 ex parte.wpd